

BOX ASSIGNMENTS

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Attorney Docket No. 2695-0009

To the Assistant Commissioner of Patents a

Sir: Please Record the Attached Original Document(s) or Copy 1 nereof.

1. Name of Conveying Party(ies):

1. ALCAZAR, Ross	2. MENG, Jie	3.
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Additional Name(s) of Conveying Party(ies) Attached? YES NO

TITLE OF INVENTION	A METHOD FOR INSERT MOLDING GLASS OR AN INORGANIC MATERIAL
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2. Party(ies) Receiving Interest:

Name and Address	Hi-P International Limited 11 International Business Park, Jurong East Singapore 609926 Republic of Singapore
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Additional Name(s) & Address(es) of Assignee(s) Attached? YES NO

3. Nature Of Conveyance (Document):

Assignment of:	<input checked="" type="checkbox"/> Whole	<input type="checkbox"/> Part Interest
<input type="checkbox"/> Original	<input checked="" type="checkbox"/> Facsimile/Photocopy	<input type="checkbox"/> Change of Name

Execution Date(s) on the Conveyance: 10/13/2010; 11/01/2010

Execution Date(s) on the Declaration if Filed Herewith: 10/13/2010; 11/01/2010

4. Application No(s). or Patent No(s). Others on Additional Sheet(s) Attached? YES NO

12/736969

Appl. Serial No.	Docket No.	1 st Inventor if not in Item 1	Patent No.	Issue Date	1 st Inventor if not in Item 1
New Application	2695-0009				

5. Name and Address of Party to Whom Correspondence Involving Document Should be Mailed: Brian Siritzky, Ph.D. Davidson Berquist Jackson & Gowdey, LLP 4300 Wilson Boulevard, 7 th Floor Arlington, VA 22203	7. Number Involved: Applications: 1 + Patents: 0 = Total: 1
6. Attorney Docket: 2695-0009	8. Amount of Fee Enclosed: (Code 581) Above Total x \$40.00 = \$40.00
	9. If Above Fee is Missing or Inadequate, Charge Deficiency to Deposit Account No. 501860 under Order No.: 2695-0009

10. Total number of pages including this cover sheet, attachments and document: 5

11. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

11/30/2010 KWHITE1 0000000/ 501860 12736969
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CUSTOMER NUMBER
42624

Respectfully submitted,

By: Brian Siritzky
Brian Siritzky, Ph.D.
Registration No. 37,497

Date: November 15, 2010

Davidson Berquist Jackson & Gowdey LLP
Phone: 703.894.6400 • Fax: 703.894.6430

PATENT
REEL: 025318 FRAME: 0590

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Attorney Docket No. 2695-0009

ASSIGNMENT of Patent Rights

(Inventors) **Ross ALCAZAR** of 2252 Blackburn Court, Aurora, Illinois 60503, U.S.A.
Jie MENG of BaoShanQu ShangDa RD, #1288-75-801, Shanghai, People's Republic of China

In consideration of the sum of one dollar (\$1.00) and other good valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to **Hi-P International Limited** ("ASSIGNEE"), a corporation of Singapore, having an office and place of business at 11 International Business Park, Jurong East, Singapore 609926, the undersigned's entire right, title and interest in the invention, all applications filed therefor for patent in the United States and in foreign countries (including divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexamination applications, extensions, and all other patent applications that have been or shall be filed on the invention), all Letters Patent (including original patents, reissued patents, reexamination certificates, and extensions) which may be granted therefor in the United States and in foreign countries, and all rights of priority resulting from the filing of any such application, for the invention known as:

(Title) **A METHOD FOR INSERT MOLDING GLASS OR AN INORGANIC MATERIAL**

for which the undersigned has already filed application Serial No. PCT/SG2010/000016 on January 22, 2010.

The undersigned acknowledges an obligation of assignment of this invention to ASSIGNEE at the time the invention was made.

The undersigned agrees to execute all papers and documents necessary in connection with the application or any interference which may be declared and any continuing or divisional applications thereof and also to execute separate assignments in connection with such applications as **Hi-P International Limited** may deem necessary or expedient and further to perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agrees to perform all affirmative acts which may be necessary to obtain a grant of valid United States and corresponding foreign patents to **Hi-P International Limited**.

The undersigned hereby authorizes and requests the Commissioner of Patents to issue any and all Letters Patent of the United States resulting from said application or any division or divisions or continuing applications thereof to **Hi-P International Limited**, as assignee of the entire interest, and hereby covenants that they have full right to convey the entire interest herein assigned, and that they have not executed and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of Davidson Berquist Jackson & Gowdey, LLP the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document. It is understood and agreed that ASSIGNEE's attorneys Davidson Berquist Jackson & Gowdey LLP have represented only ASSIGNEE and will continue to represent only ASSIGNEE with respect to this invention.

In witness whereof, executed by the undersigned on the dates opposite the undersigned signatures.

Date: _____ Inventor: _____ Witness: _____

Ross Alcazar

Date: 2010-10-13 Inventor: _____ Witness: _____

Jie Meng

ASSIGNMENT of Patent Rights

Acceptance Declaration

ASSIGNEE hereby agrees to and accepts the above-mentioned assignment from the inventors.

Assignee (Hi-P International Limited):

Signature:  Date: _____
Name Yao Hsiao Tung
Title Executive Chairman & CEO

ASSIGNMENT of Patent Rights

(Inventors) **Ross ALCAZAR** of 2252 Blackburn Court, Aurora, Illinois 60503, U.S.A.
Jie MENG of BaoShanQu ShangDa RD, #1288-75-801, Shanghai, People's Republic of China

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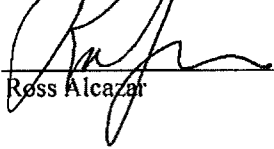
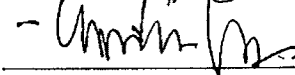
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In witness whereof, executed by the undersigned on the dates opposite the undersigned signatures.

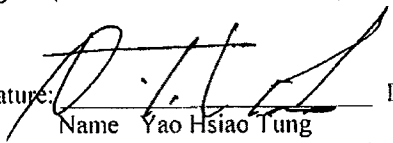
Date: 11-1-10 Inventor:  Witness: 
Date: _____ Inventor: _____ Witness: _____
Jie Meng

ASSIGNMENT of Patent Rights

Acceptance Declaration

ASSIGNEE hereby agrees to and accepts the above-mentioned assignment from the inventors.

Assignee (Hi-P International Limited):

Signature:  Date: _____
Name Yao Hsiao Tung
Title Executive Chairman & CEO